



Material Content Data Sheet



Sales Product Name				BTS141TC		Issued		20. July 2018	
MA#				MA000701084					
Package				PG-TO263-3-2		Weight*		1543.31 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.251	0.53	0.53	5346	5346	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		197		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	copper	7440-50-8	304.026	19.70	19.73	196996	197252	
wire	non noble metal	aluminium	7429-90-5	1.442	0.09	0.09	935	935	
encapsulation	organic material	carbon black	1333-86-4	7.319	0.47		4742		
	inorganic material	antimonytrioxide	1309-64-4	15.304	0.99		9916		
	plastics	brominated resin	-	17.300	1.12		11209		
	plastics	epoxy resin	-	126.421	8.19		81915		
	inorganic material	silicondioxide	60676-86-0	499.029	32.34	43.11	323350	431132	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.63	0.63	6257	6257	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		148		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	148	
glue	plastics	Polyimide	26023-21-2	0.157	0.01	0.01	101	101	
solder	noble metal	silver	7440-22-4	0.135	0.01		88		
	non noble metal	tin	7440-31-5	0.108	0.01		70		
	non noble metal	lead	7439-92-1	5.161	0.33	0.35	3344	3502	
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		355		
	inorganic material	phosphorus	7723-14-0	0.165	0.01		107		
	non noble metal	copper	7440-50-8	547.666	35.49	35.54	354864	355327	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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